MATERION

Data Sheet

PC-RAM Materials

Enabling the PC-RAM industry with high-purity thin film materials.

The global advanced memory market continues to expand rapidly, creating the need for next-generation material solutions. The industry depends on the development of new alloys for Phase-Change Random Access Memory (PC-RAM) customized to meet the demand for highly defined composition, size, purity, and consistency.

Materion manufactures critical materials to support advanced memory and data storage applications and allows its customers to excel in this rapidly evolving market. We offer more than 50 years of experience working with heavy metals and chalcogenides, such as Germanium-Antimony-Tellurium (GST) compositions, in addition to our production capabilities to manufacture a range of high-purity thin film materials. We customize each order to match our customers' needs for unique alloys, scaled for R&D or production size. Using highly controlled processing technologies, we manufacture diverse compositions to meet our customers' stringent specifications.

AVAILABLE ALLOYS & COMPOUNDS CONTAINING

- Germanium
- Arsenic
- Selenium
- Antimony
- Tellurium
- Silicon

AVAILABLE FORMS

- Targets for a variety of OEM platforms and custom configurations
- Scalable sizes for 300mm wafer production

SPECIALIZED EXPERTISE

- Application scientists available for collaborative development
- Experienced with heavy metals – Poisonous & Deleterious Substances Control License
- Knowledgeable in materials for OTS applications
- Full analytical capabilities (composition and purity)
- Processes in place for low oxygen alloys

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BENEFITS

In addition to our unique materials and processes, we offer:

- Technical expertise in developing alloys
- Vertically integrated raw material and target manufacturing processes
- Clean room packaging that meets semiconductor standards
- Manufactured in the USA
- Compatible with all standard OEMs

RELATED SERVICES

- Backing plates
- Target bonding
- On-site application support